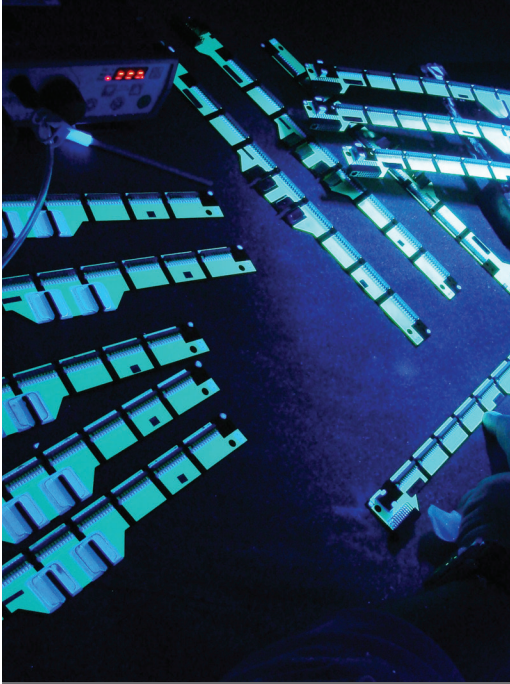




ZENTECH

RF CONTRACT MANUFACTURING AND ENGINEERING SERVICES

» IPCJ-STD-001 » ISO 9001 » AS9100 » ITAR Registered » DD2345 » ISO 13485 » IPC Class 3 Trusted Source » IPC 1791



CONTACT ZENTECH

www.zentech.com
sales@zentech.com

6980 Tudsbury Road
Baltimore, Maryland 21244
(443) 348-4500

3361 Shannon Airport Circle
Fredericksburg, VA 22408
(540) 372-6500



LEADERSHIP

Zentech's senior management team has broad experience in the RF, Defense, Medical and Telecom Industries, providing a foundation for establishing advanced quality systems and processes. Providing RF product realization services from concept through full life cycle management, Zentech has a proven track record of successful RF programs in a variety of disciplines. Zentech operates out of an ITAR registered, ISO compliant facilities in Baltimore, MD and Fredericksburg, VA and is an engineering-driven, agile facility equally experienced in New Product Introduction (NPI) and Program Level manufacture of RF assemblies.

RF DISCIPLINE EXPERIENCE

- Phased and parasitic arrays
- Inter-Digital Filters
- VHF/UHF Strip Line Filters
- Low Noise Amplifier
- Dispersive Medium Time Domain Reflectometry (TDR)
- Noise Interval Blanking
- Receiver Design
- Multi kW HF and VHF Systems

RF PRODUCT APPLICATIONS

- Transmitters / Receivers
- RF Backhaul Video Equipment
- RF-based IED and other Detection Sub-Systems
- GPS, GSM and CDMA Systems
- RF Antennas and Arrays
- Smart Grid Metering Systems
- Radar-Based Systems
- Broadband / JTRS Radios
- Wi-Fi, Wi-Max and ZigBee Systems

RF MANUFACTURING PROCESS

NPI/Production/Testing/Tuning and Sustaining Engineering

Zentech deploys a cell-based, incremental processing system for RF manufacturing with complete and detailed step-by-step pictorial assembly instructions to insure process repeatability and product reliability:

- IPC J-STD 001 (with Space) Certification Soldering Processes and Personnel
- Indium Silver (In/Ag) Processes for Sweat Soldering Devices into PCB Cavities
- 3D SPI (Solder Paste Inspection)
- High-Precision SMT Placement
- Leaded and RoHs Processes
- Fully Automatic and Semi-Automatic Stencil Printing
- Automated Optical Inspection (AOI)
- Placement of BGAs, Micro BGAs and Flip Chips to 0.3 mm, to 0.2mm for Advanced Technologies
- BGA X-Ray and BGA Rework Capabilities
- Special Coatings including Potting and Conformal Coat
- Component Underfill and other various types of Bonding
- Mechanical Assembly and Chassis Integration
- Process and Test Fixture Development
- ESS (Environmental Stress Screening) and HASS (Highly Accelerated Stress Screening) Cyclic and Cryogenic Shock Testing Capable
- Functional Test and Troubleshooting
- Point to Point Wiring and Harnessing
- Thermal Profiling for Metal-core and Metal-backed PCB's built on Rogers and Taconic Materials
- Failure Analysis and Compliance Testing Coordination
- Process, Test Procedure and Test Fixture Development